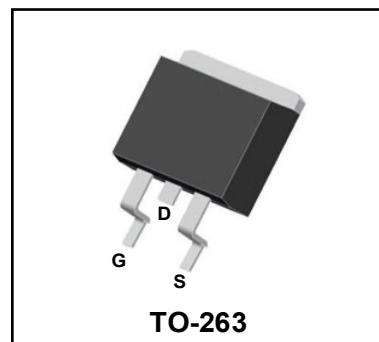


# WMM053NV8HGS

## 85V N-Channel Enhancement Mode Power MOSFET

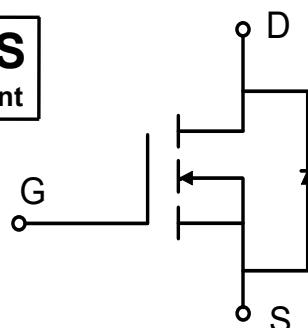
### Description

WMM053NV8HGS uses Wayon's advanced power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.



### Features

- $V_{DS} = 85V$ ,  $I_D = 125A$
- $R_{DS(on)} < 5.5m\Omega$  @  $V_{GS} = 10V$
- High Speed Power Switching
- Low Gate Charge
- Low  $R_{DS(ON)}$
- 100% EAS Guaranteed



### Applications

- Battery Management System
- Power Management Switching
- Motor Drive

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	85	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current  $T_C = 25^\circ C$	$I_D$	125	A
		79	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	500	A
Single Pulse Avalanche Energy <sup>2</sup>	$EAS$	273.8	mJ
Total Power Dissipation	$P_D$	162	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	58	$^\circ C/W$
Thermal Resistance from Junction-to-Lead	$R_{\theta JC}$	0.77	$^\circ C/W$

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	85	-	-	V
Gate-body Leakage current	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$I_{\text{DSS}}$	$V_{\text{DS}} = 85\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	$\mu\text{A}$
$T_J=100^\circ\text{C}$			-	-	100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2	3	4	V
Drain-Source on-Resistance <sup>4</sup>	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	-	4.2	5.5	$\text{m}\Omega$
Forward Transconductance <sup>4</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 5\text{V}, I_D = 20\text{A}$	-	55	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	4645	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	673	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	41	-	
Gate Resistance	$R_G$	$f = 1\text{MHz}$	-	1.8	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 40\text{V}, I_D = 20\text{A}$	-	61.3	-	$\text{nC}$
Gate-Source Charge	$Q_{gs}$		-	21	-	
Gate-Drain Charge	$Q_{gd}$		-	11	-	
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 40\text{V}, R_G = 3\Omega, I_D = 20\text{A}$	-	16.5	-	$\text{ns}$
Rise Time	$t_r$		-	51.8	-	
Turn-off Delay Time	$t_{\text{d(off)}}$		-	21	-	
Fall Time	$t_f$		-	11	-	
Body Diode Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 20\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	69	-	$\text{ns}$
Body Diode Reverse Recovery Charge	$Q_{\text{rr}}$		-	141	-	$\text{nC}$
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{\text{SD}}$	$I_S = 20\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	1.2	V
Continuous Source Current	$T_C = 25^\circ\text{C}$	$I_S$	-	-	125	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})} = 150^\circ\text{C}$ .
2. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}} = 25\text{V}, V_{\text{GS}} = 10\text{V}, L = 0.4\text{mH}, I_{\text{AS}} = 37\text{A}$ .
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test.

## Typical Characteristics

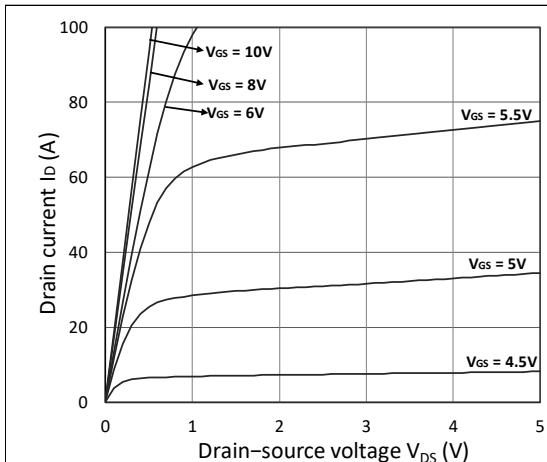


Figure 1. Output Characteristics

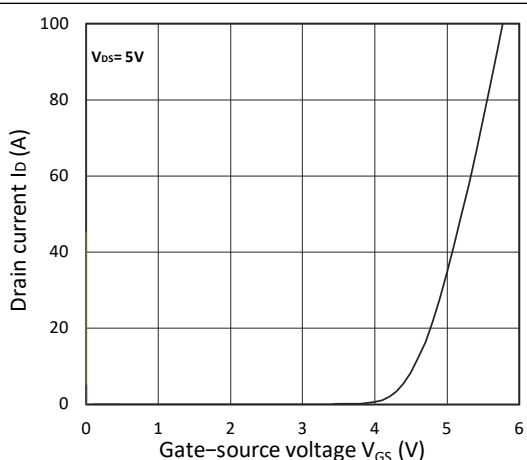


Figure 2. Transfer Characteristics

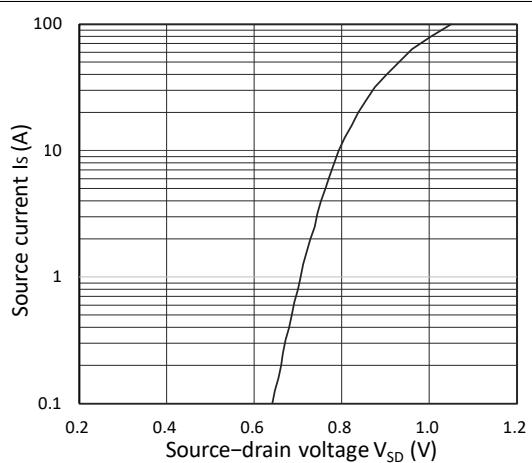
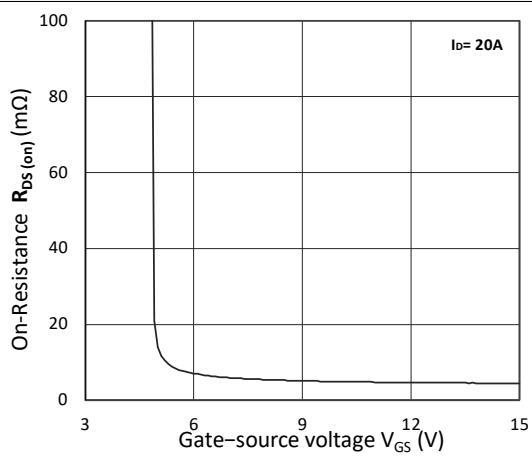
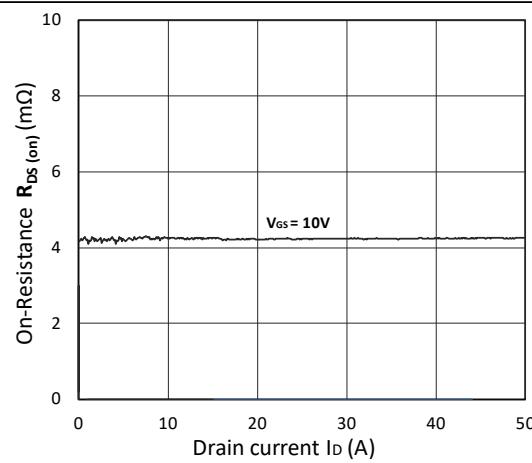
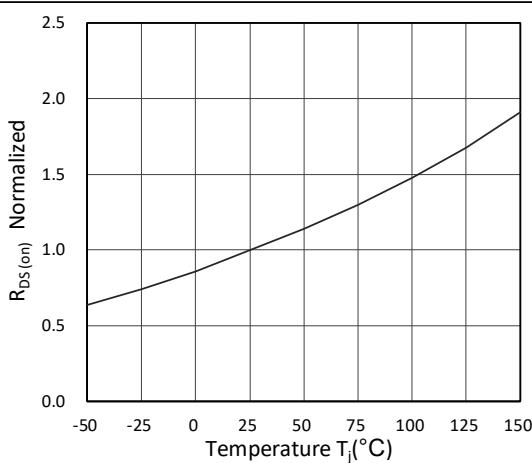
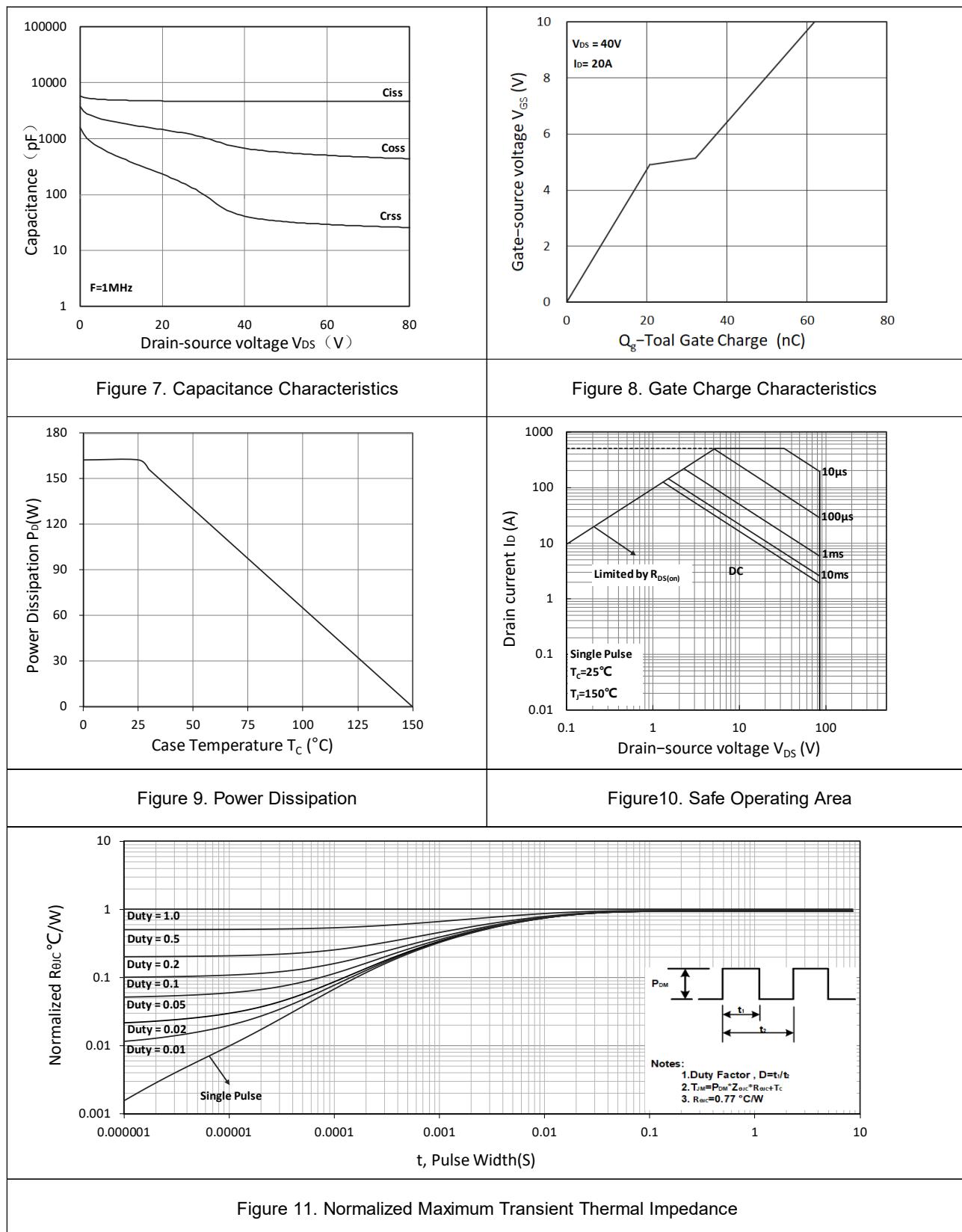
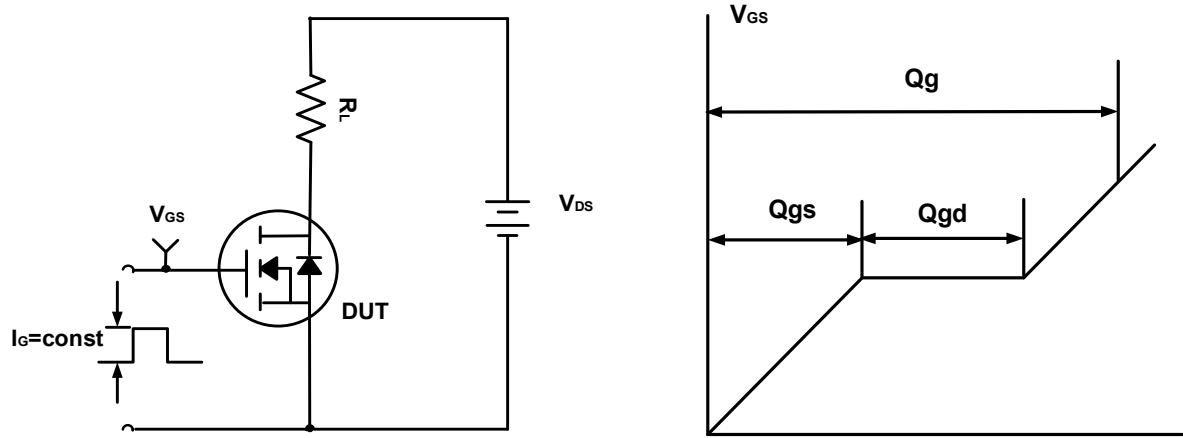
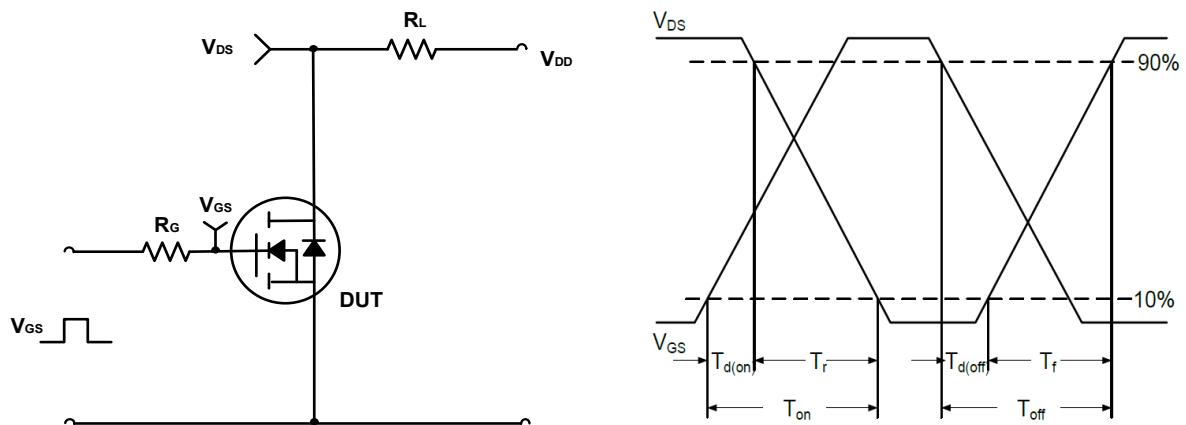
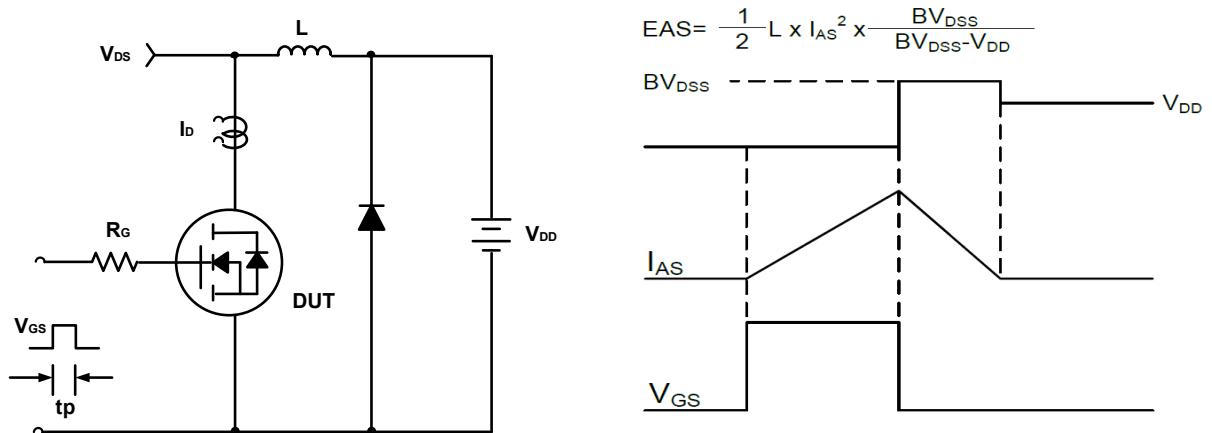


Figure 3. Forward Characteristics of Reverse

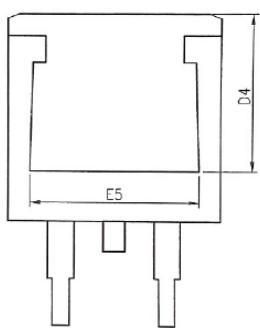
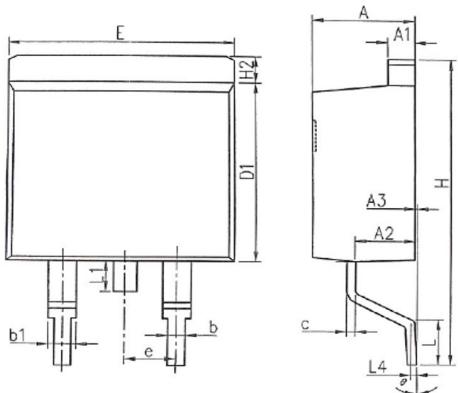
Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(on)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature



**Test Circuit****Figure A. Gate Charge Test Circuit & Waveforms****Figure B. Switching Test Circuit & Waveforms****Figure C. Unclamped Inductive Switching Circuit & Waveforms**

## Mechanical Dimensions for TO-263

## COMMON DIMENSIONS



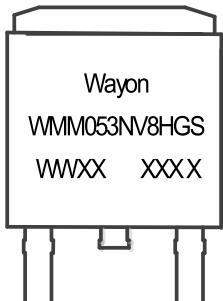
SYMBOL	MM	
	MIN	MAX
A	4.37	4.89
A1	1.17	1.42
A2	2.20	2.90
A3	0.00	0.25
b	0.70	0.96
b1	1.17	1.47
c	0.28	0.60
D1	8.45	9.30
D4	6.60	-
E	9.80	10.40
E5	7.06	-
e	2.54BSC	
H	14.70	15.70
H2	1.07	1.47
L	2.00	2.80
L1	-	1.75
L4	0.254BSC	
θ	0°	9°

# **WMM053NV8HGS**

## **Ordering Information**

<b>Part</b>	<b>Package</b>	<b>Marking</b>	<b>Packing method</b>
WMM053NV8HGS	TO-263	WMM053NV8HGS	Tape and Reel

## **Marking Information**



**WMM053NV8HGS = Device code**

**WWXX XXX X= Date code**